

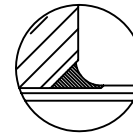
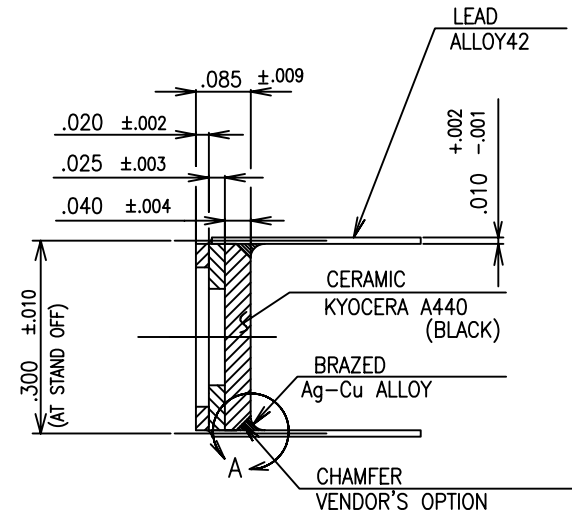
PART No.	NOTCH AREA METALLIZED
1	WITH METALLIZATION
2	WITHOUT METALLIZATION

LEAD NO.1

INDEX MARK
PLATING OPTION

TYP.
.020R

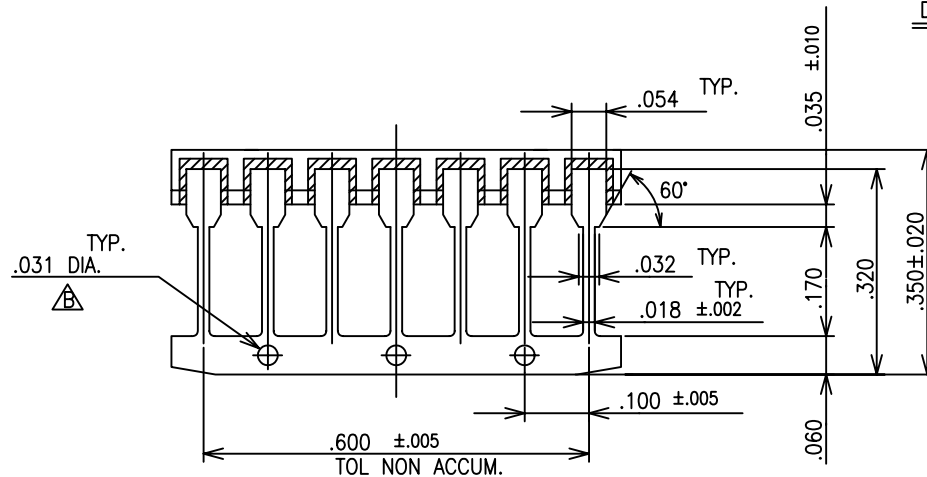
TYP.
.032R



DETAIL-A

NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEAD.
5. LEAD RESISTANCE: 0.2 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDING OUTER LEAD.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.



SB014K290-2	S=0
	D=0
SB014K290-1	S=0
	D=0

DRAWN	CHECKED	APPROVED	DATE
H.K	K.M		JUN.19.'80

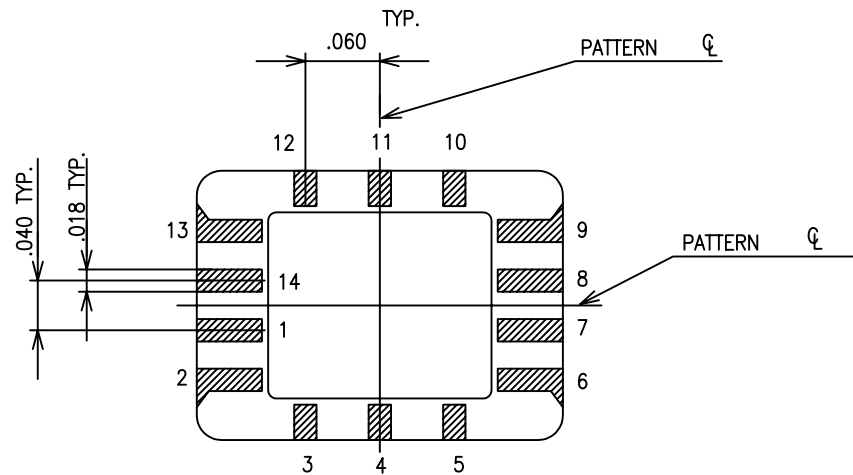
MODIFICATION	DESCRIPTION	DATE	BY	TO	DATE	BY	TO	DATE	BY
	DELETED : VENDOR'S OPTION.		S.NI	T.O.H/M.S.U		H.SA			
△	ADDED : PART No.02, NOTE.6,7.								
△	REDRAWN (CONVERTED CAD DATA)		S.F	T.C/K.M		T.A			
	CHANGED	DATE	DRAWN	CHECKED		APPROVED			

NAME	14 LEAD SIDE BRAZED PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED
SCALE	5/1	MATERIAL	AS INDICATED
		KYOCERA CORPORATION KYOTO JAPAN	

DRAWING NO.	KD-80290-B	SHEET	1/2
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SSM P/N: CSB01438



BONDING PATTERN

MODIFICATION						NAME 14LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.F	CHECKED T.C	APPROVED T.A	DATE OCT.15.'93
						SCALE 10 / 1	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-80290-B	SHEET 2/2		



